RENESAS

HSK120

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0192-0400Z (Previous: ADE-208-171C) Rev.4.00 Mar.22.2004

Features

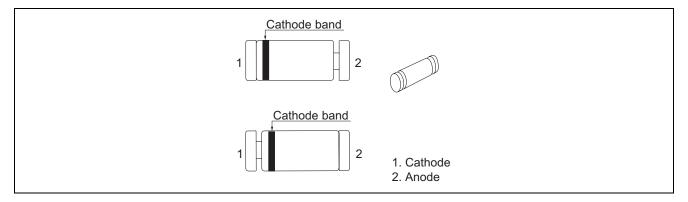
• Low reverse recovery time. $(t_{rr} = 3.0 \text{ ns max})$

• LLD package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Туре No.	Laser Mark	Package Code
HSK120	White	LLD

Pin Arrangement





Absolute Maximum Ratings

			(Ta = 25°C)
Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM}	70	V
Reverse voltage	V _R	60	V
Peak forward current	I _{FM}	450	mA
Non-Repetitive peak forward surge current	I _{FSM} * ¹	4	А
Average rectified current	lo	150	mA
Junction temperature	Тј	175	°C
Storage temperature	Tstg	-65 to +175	°C

Note: 1. Within 1µs forward surge current.

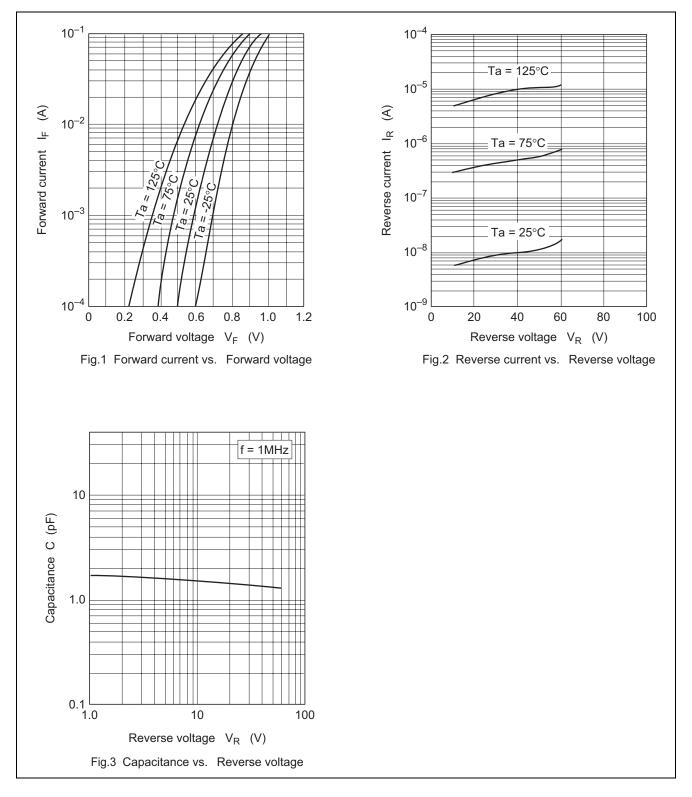
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.8	V	I _F = 10 mA
Reverse voltage	V _R	70	_	_	V	I _R = 5 μA
Reverse current	I _R	_	_	0.1	μΑ	V _R = 60 V
Capacitance	С	_	_	3.0	pF	$V_{R} = 0 V, f = 1 MHz$
Reverse recovery time	t _{rr}	_		3.0	ns	$I_F=10~mA,~V_R=6~V,~R_L=50~\Omega,~I_{rr}=0.1I_R$

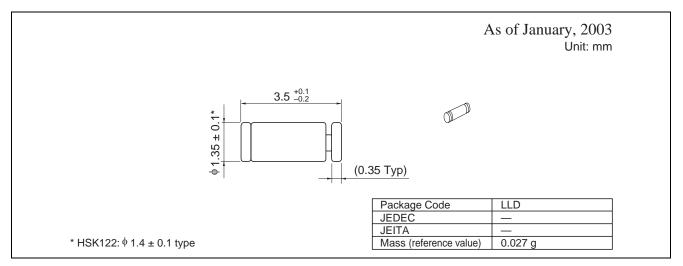


Main Characteristics



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Package Dimensions





Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

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Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500 Fax: <1> (408) 382-7501

Renesas Technology Europe Limited. Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

Renesas Technology Europe GmbH Dornacher Str. 3, D-85622 Feldkirchen, Germany Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

Renesas Technology Hong Kong Ltd. 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2375-6836

Renesas Technology Taiwan Co., Ltd. FL 10, #99, Fu-Hsing N. Rd., Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. 26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd. 1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

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